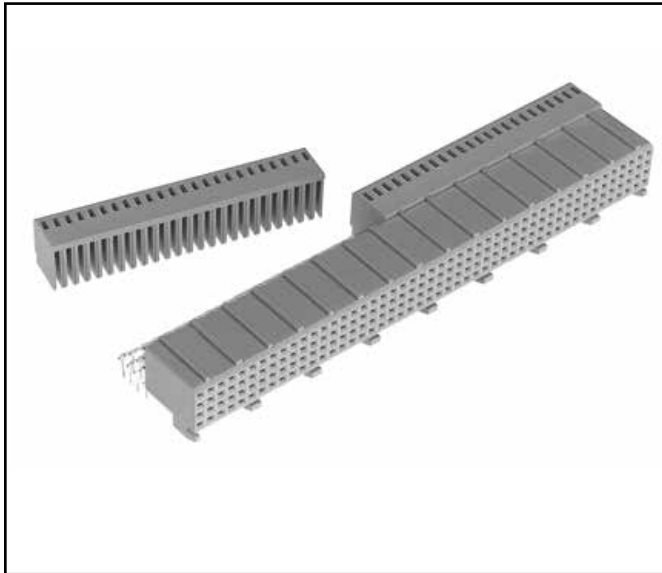


3M™ MetPak™ 2-FB Socket

2 mm 4/5-Row, Solder Tail or Press-Fit With Tail Cover, Right Angle

MP2 Series



- End-to-end stackable
- Offset dual-beam contact minimizes insertion force
- Expanded pin counts
- Protective Push-Cap
- Monoblockable
- Press or heat stake peg
- 12 mm modular units
- Meets global IEC 61076-4-104 Futurebus+® standard
- See the Regulatory Information Appendix (RIA) in the “RoHS compliance” section of www.3Mconnectors.com for compliance information (RIA E1 & C1 apply)

Date Modified: September 17, 2013

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Physical

Insulation:

Material: High Temp LCP
Flammability: UL 94V-0
Color: Beige

Contact:

Material: Copper Alloy

Plating:

Underplating: 50 μ” (1.27 μm) Nickel
Wiping Area: See Ordering Information
Solder Tails: See Ordering Information

Electrical

Current Rating: Signal: 1.5 A - All contacts simultaneously

Insulation Resistance: 10³ MΩ

Withstanding Voltage: 1,000 V_{AC}

Environmental

Temperature Rating: -55° C to 125° C

Process Temperature Rating: 260°C (Profile per J-STD-020C)

Moisture Sensitivity Level: 1 (per J-STD-020C)

UL File No.: E68080

MetPak is a trademark of 3M Company.
Futurebus+ is a registered trademark of the Institute of Electrical and Electronic Engineers, Inc. (IEEE)

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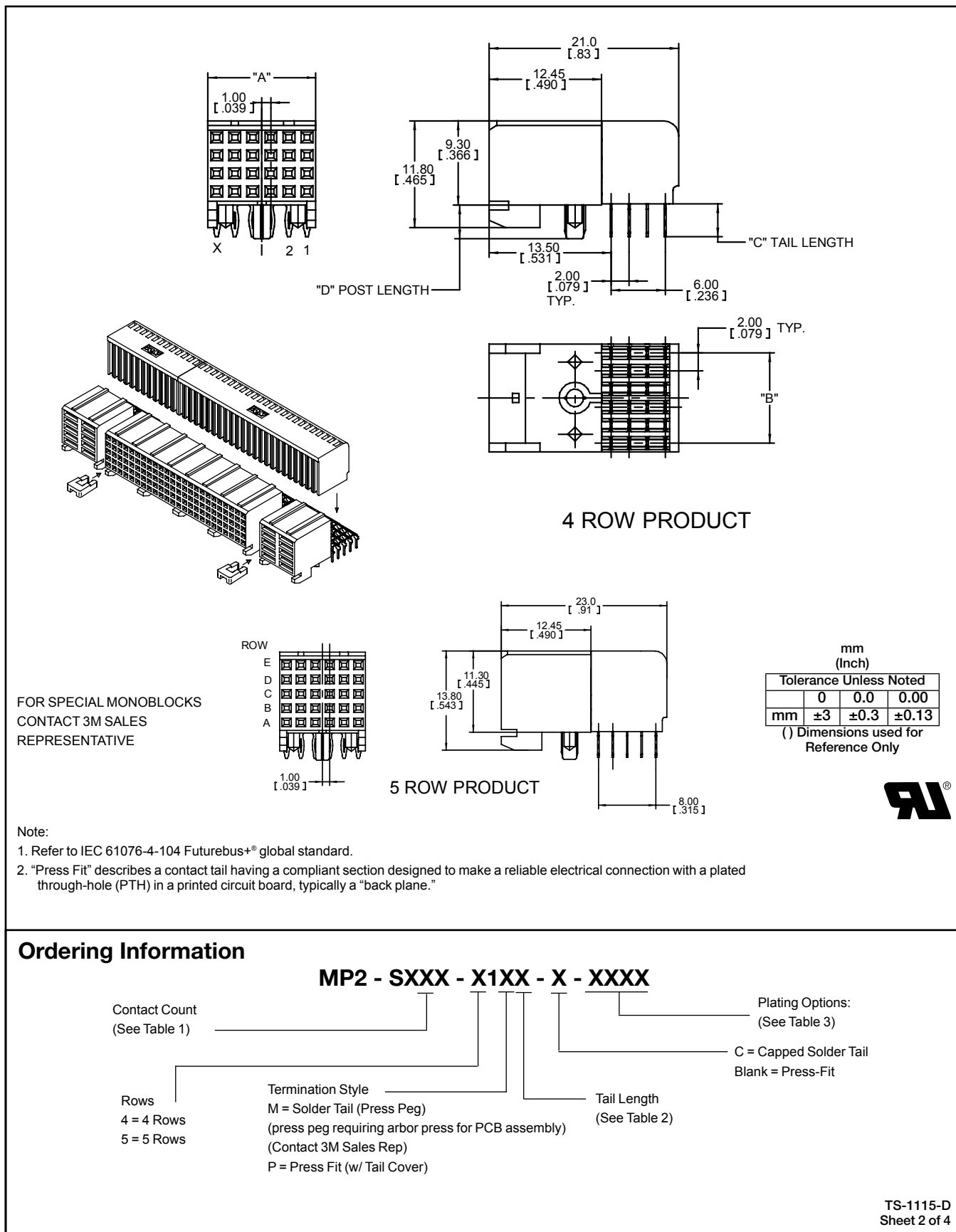
Electronic Solutions Division
Interconnect Solutions
<http://www.3Mconnectors.com>

3M is a trademark of 3M Company.
For technical, sales or ordering information call
800-225-5373

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Table 1 - Connector & Row Lengths						
Pin Count	Dim "A" mm (Inch)		Dim "B" mm (Inch)		Rows	Block Count
024	11.95	[0.471]	10.00	[0.394]	4	1
048	23.95	[0.943]	22.00	[0.866]	4	2
072	35.95	[1.415]	34.00	[1.339]	4	3
096	47.95	[1.889]	46.00	[1.811]	4	4
120	59.95	[2.36]	58.00	[2.283]	4	5
144	71.95	[2.833]	70.00	[2.756]	4	6
168	83.95	[3.305]	82.00	[3.228]	4	7
192	95.95	[3.778]	94.00	[3.701]	4	8
030	11.95	[0.471]	10.00	[0.394]	5	1
060	23.95	[0.943]	22.00	[0.866]	5	2
090	35.95	[1.415]	34.00	[1.339]	5	3
120	47.95	[1.888]	46.00	[1.811]	5	4
150	59.95	[2.361]	58.00	[2.283]	5	5
180	71.95	[2.833]	70.00	[2.756]	5	6
210	83.95	[3.305]	82.00	[3.228]	5	7
240	95.95	[3.778]	94.00	[3.701]	5	8

Table 2 - Tail & Post Lengths			
Contact-to-PC Board Tail Termination Option No.		Dim "C"	Dim. "D"
Solder	Press-Fit*		
M1		2.72 [0.107]	3.57 [0.141]
M2	P1	3.53 [0.139]	3.57 [0.141]

*Compliant-Pin Tail

Table 3 - Plating			
Plating Suffix	Press-Fit Tails*	Solder Tails	Plating Composition
KR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.76 µm [30 µ"] Min. Au Contact Area 2.54 µm [100 µ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 µm [50 µ"] Min. Ni all over
LR	(RIA E1 & C1 apply)	(RIA E1 & C1 apply)	0.08 µm [3 µ"] Min. Au Contact Area 0.67 µm [27 µ"] Min. PdNi Contact Area 2.54 µm [100 µ"] Min. Matt Whisker Mitigating Sn Tail Area 1.27 µm [50 µ"] Min. Ni all over

*Compliant-Pin Tail

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2 mm 4/5-Row, Solder Tail or Press-Fit With Tail Cover, Right Angle

MP2 Series

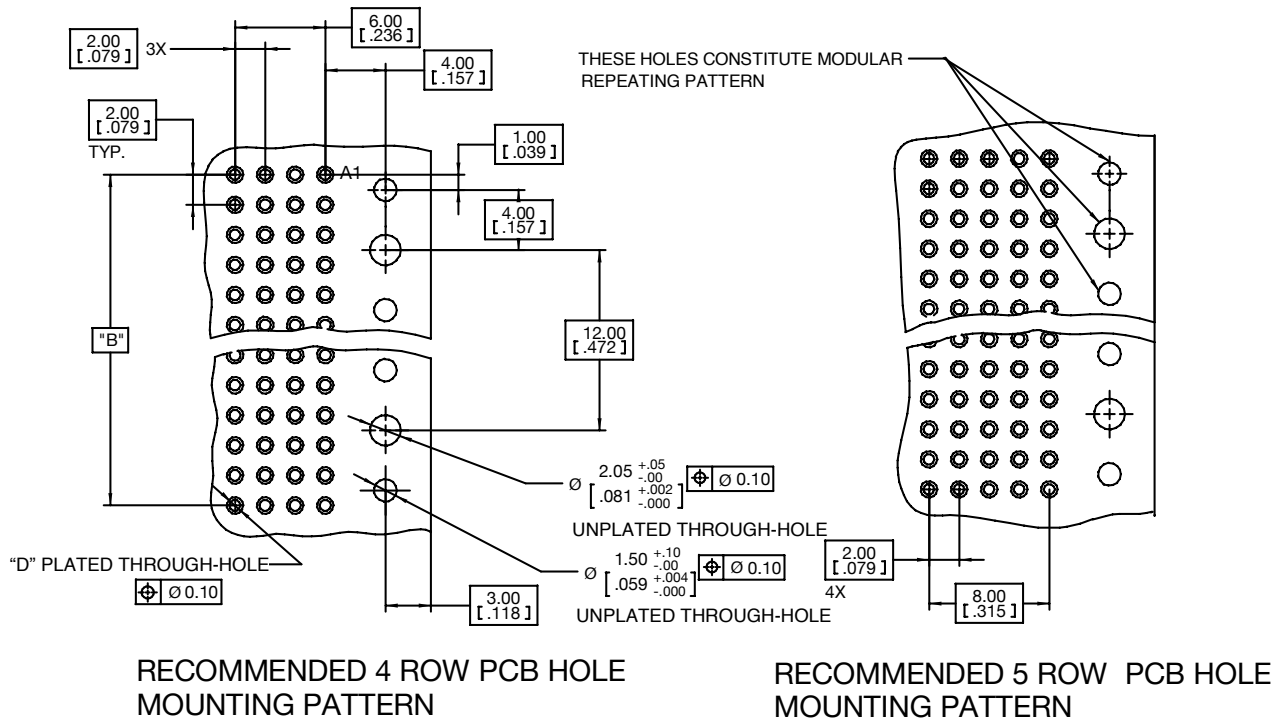


Table 4: HOLE PLATING FINISHES

HOLE	Finished Dia. mm [in]	Cu Thickness mm [in]	Immersion Matte Sn Thickness microns [μm]	Electrolytic Au Thickness microns [μm]	OSP ENTEK Thickness microns [μm]	Drilled Hole Dia. mm [in]
"D"	0.700-0.800 [.0276-.0315]	0.025-0.045 [0.001-0.002]	0.5 - 2.5 [20 - 100]	0.1 - 0.5 [4 - 20]	0.2 - 0.5 [8 - 20]	0.830-0.860 [.0330-.0340] or 0.85mm [#66] TWIST DRILL

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